

Ultrafast Dual Diode

30 A, 200 V

RURG1520CC

Description

The RURG1520CC is an ultrafast dual diode with low forward voltage drop. This device is intended for use as freewheeling and clamping diodes in a variety of switching power supplies and other power switching applications. It is specially suited for use in switching power supplies and industrial application.

Features

- Ultrafast Recovery $t_{rr} = 35 \text{ ns}$ (@ $I_F = 15 \text{ A}$)
- Max Forward Voltage, $V_F = 1.05 \text{ V}$ (@ $T_C = 25^\circ\text{C}$)
- Reverse Voltage, $V_{RRM} = 200 \text{ V}$
- Avalanche Energy Rated
- This Device is Pb-Free and is RoHS Compliant

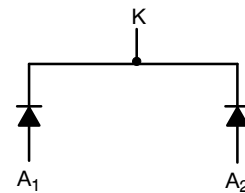
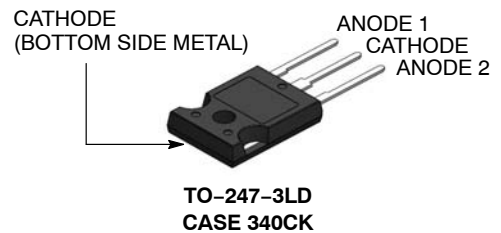
Applications

- Switching Power Supplies
- Power Switching Circuits
- General Purpose

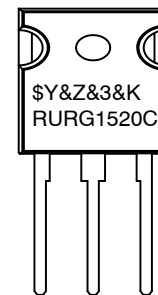


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MARKING DIAGRAM



\$Y	= ON Semiconductor Logo
&Z	= Assembly Plant Code
&3	= Numeric Date Code
&K	= Lot Code
RURG1520C	= Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

RURG1520CC

ABSOLUTE MAXIMUM RATINGS (Per Leg) ($T_C = 25^\circ\text{C}$)

Parameter	Symbol	Ratings	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	200	V
Working Peak Reverse Voltage	V_{RWM}	200	V
DC Blocking Voltage	V_R	200	V
Average Rectified Forward Current ($T_C = 157^\circ\text{C}$)	$I_{F(AV)}$	15	A
Repetitive Peak Surge Current (Square Wave, 20 kHz)	I_{FRM}	30	A
Nonrepetitive Peak Surge Current (Halfwave, 1 Phase, 60 Hz)	I_{FSM}	200	A
Maximum Power Dissipation	P_D	100	W
Avalanche Energy (See Figures 7 and 8)	E_{AVL}	20	mJ
Operating and Storage Temperature	T_{STG}, T_J	-65 to 175	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

PACKAGE MARKING AND ORDERING INFORMATION

Device	Device Marking	Package	Shipping
RURG1520CC	RURG1520C	TO-247-3LD	450 / Tube

ELECTRICAL CHARACTERISTICS (Per Leg) ($T_C = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Instantaneous Forward Voltage (Pulse Width = 300 μs , Duty Cycle = 2%)	V_F	$I_F = 15\text{ A}$	-	-	1.05	V
		$I_F = 15\text{ A}, T_C = 150^\circ\text{C}$	-	-	0.85	V
Reverse Leakage (Instantaneous Reverse Current)	I_R	$V_R = 200\text{ V}$	-	-	100	μA
		$V_R = 200\text{ V}, T_C = 150^\circ\text{C}$	-	-	500	μA
Reverse Recovery Time (See Figure 6) Summation of $t_a + t_b$	t_{rr}	$I_F = 1\text{ A}, dI_F/dt = 100\text{ A}/\mu\text{s}$	-	-	30	ns
		$I_F = 15\text{ A}, dI_F/dt = 100\text{ A}/\mu\text{s}$	-	-	35	ns
Time to Reach Peak Reverse Current (See Figure 6)	t_a	$I_F = 15\text{ A}, dI_F/dt = 100\text{ A}/\mu\text{s}$	-	20	-	ns
Time from Peak I_{RM} to Projected Zero Crossing of I_{RM} Based on a Straight Line from Peak I_{RM} through 25% of I_{RM} (See Figure 6)	t_b	$I_F = 15\text{ A}, dI_F/dt = 100\text{ A}/\mu\text{s}$	-	10	-	ns
Thermal Resistance Junction to Case	$R_{\theta JC}$		-	-	1.5	$^\circ\text{C}/\text{W}$

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL PERFORMANCE CURVES

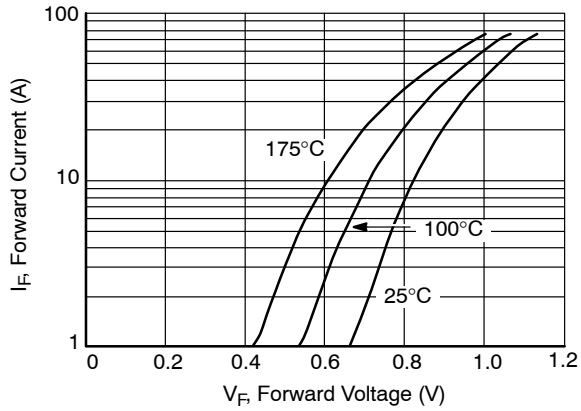


Figure 1. Forward Current vs. Forward Voltage

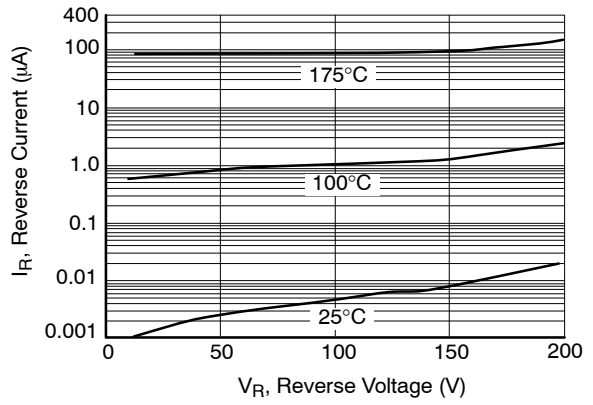


Figure 2. Reverse Current vs. Reverse Voltage

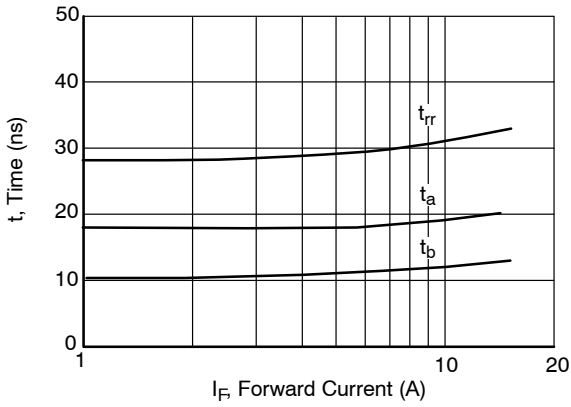


Figure 3. t_{rr} , t_a and t_b Curves vs. Forward Current

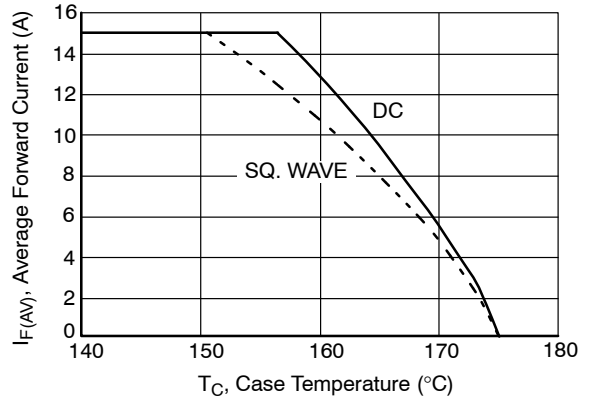


Figure 4. Current Derating Curve

TEST CIRCUITS AND WAVEFORMS

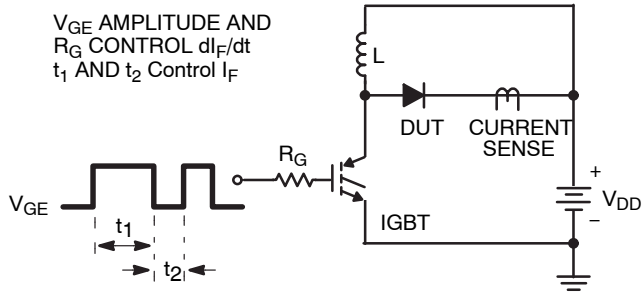


Figure 5. t_{rr} Test Circuit

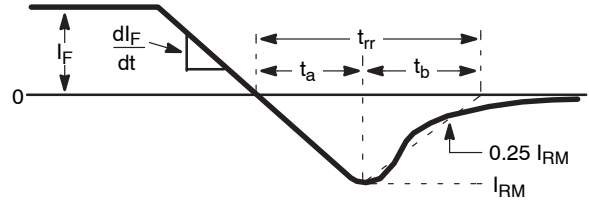


Figure 6. t_{rr} Waveforms and Definitions

$I = 1 \text{ A}$
 $L = 40 \text{ mH}$
 $R < 0.1 \Omega$
 $E_{AVL} = 1/2LI^2 [V_{R(AVL)}/(V_{R(AVL)} - V_{DD})]$
 $Q_1 = \text{IGBT } (BV_{CES} > \text{DUT } V_{R(AVL)})$

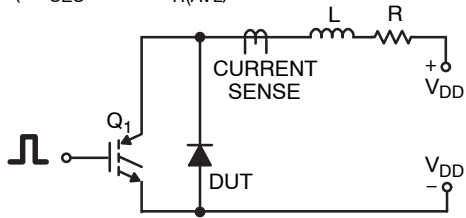


Figure 7. Avalanche Energy Test Circuit

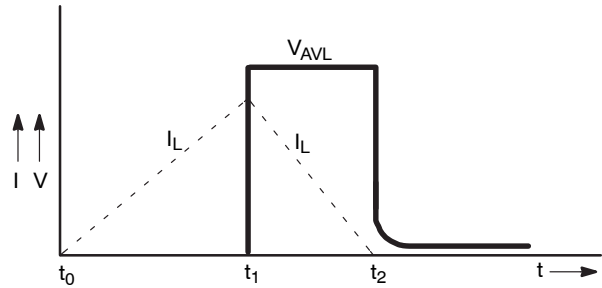


Figure 8. Avalanche Current and Voltage Waveforms

MECHANICAL CASE OUTLINE

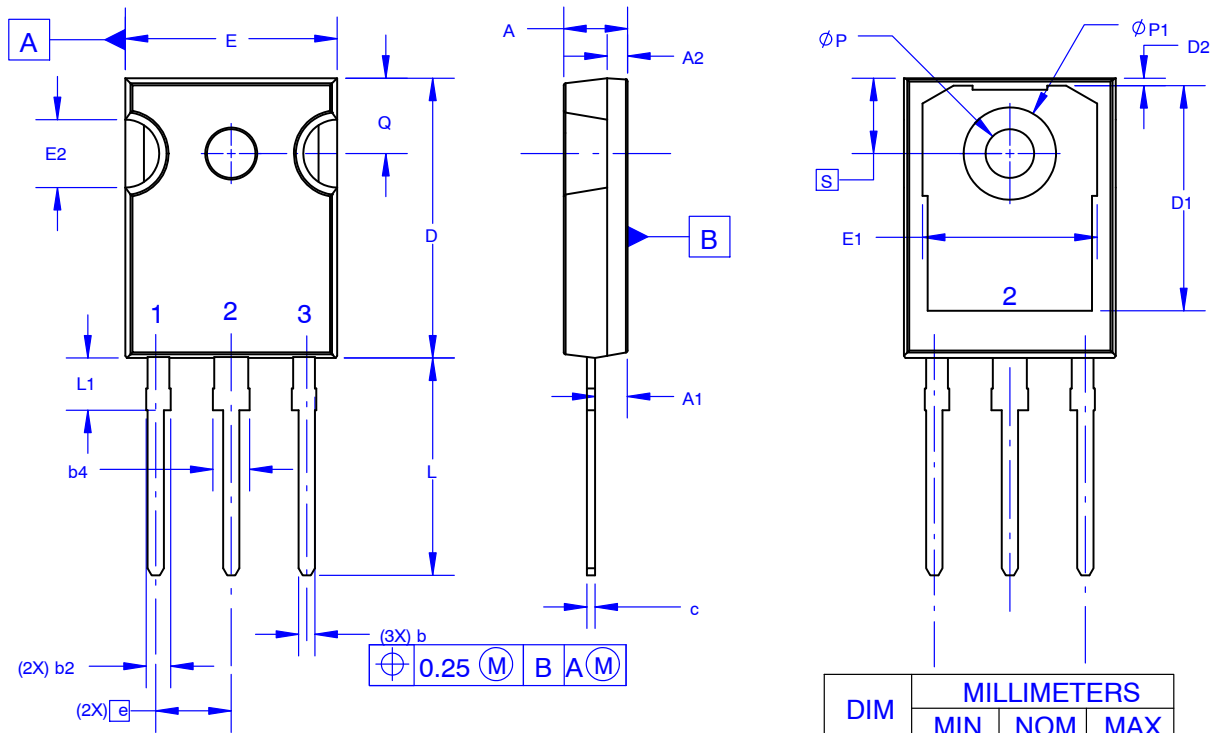
PACKAGE DIMENSIONS

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TO-247-3LD SHORT LEAD CASE 340CK ISSUE A

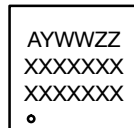
DATE 31 JAN 2019



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 - 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- ZZ = Assembly Lot Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.58	4.70	4.82
A1	2.20	2.40	2.60
A2	1.40	1.50	1.60
b	1.17	1.26	1.35
b2	1.53	1.65	1.77
b4	2.42	2.54	2.66
c	0.51	0.61	0.71
D	20.32	20.57	20.82
D1	13.08	~	~
D2	0.51	0.93	1.35
E	15.37	15.62	15.87
E1	12.81	~	~
E2	4.96	5.08	5.20
e	~	5.56	~
L	15.75	16.00	16.25
L1	3.69	3.81	3.93
ØP	3.51	3.58	3.65
ØP1	6.60	6.80	7.00
Q	5.34	5.46	5.58
S	5.34	5.46	5.58

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